

FIG. 4

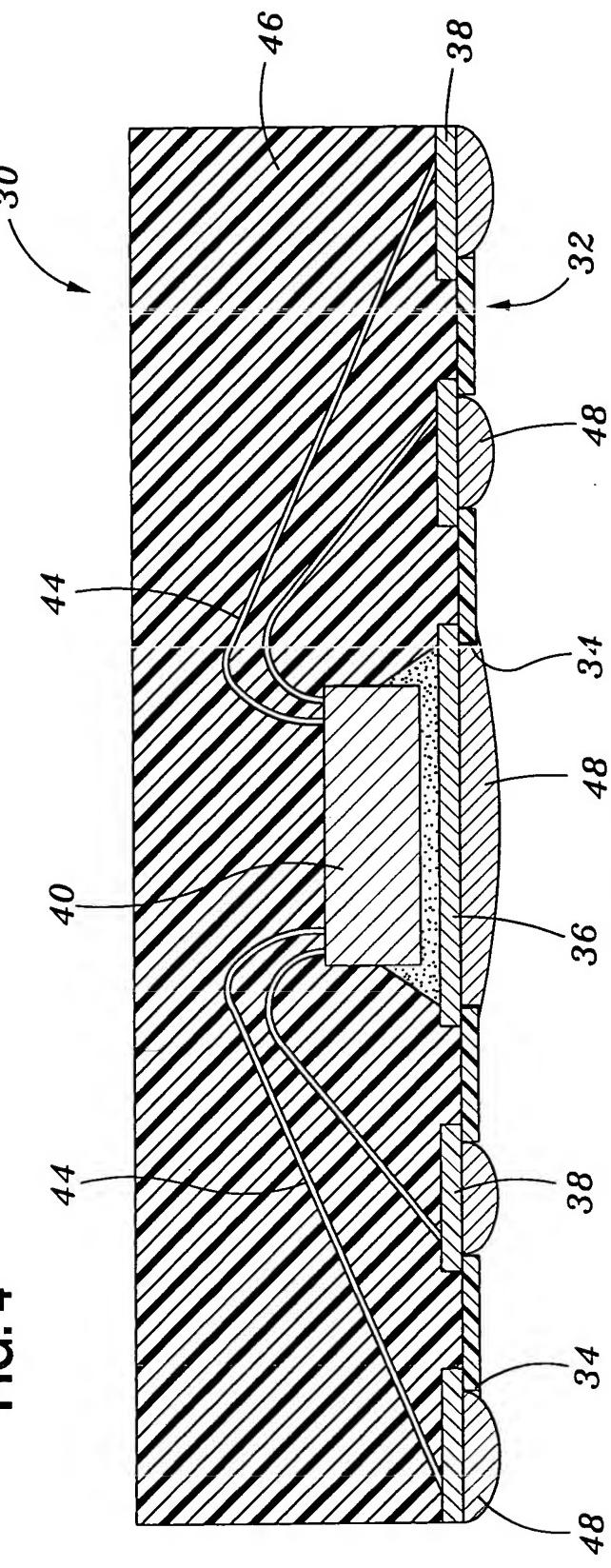


FIG. 3

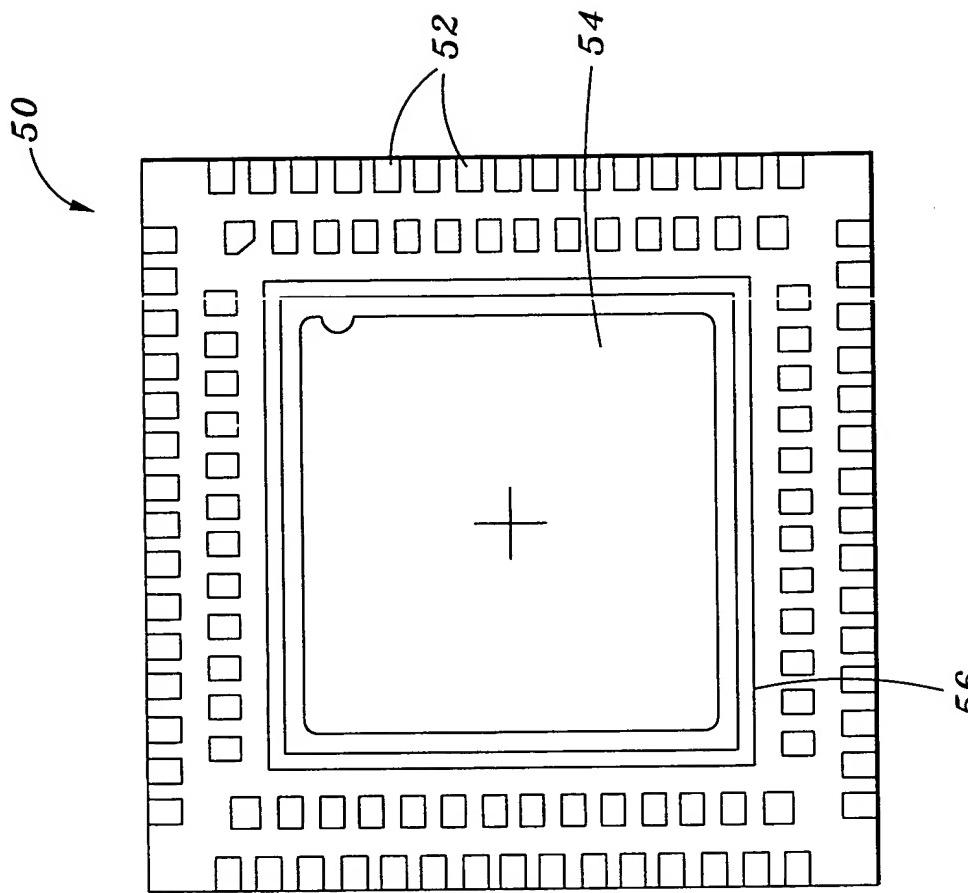


FIG. 5

| Process Flow | Chemicals | Comment |
|-----------------------|------------------------|------------------|
| Cleaning | General Acid Clean | pH 3.4 (ambient) |
| Hot Rinse | DI Water | |
| Ambient Rinse | DI Water | |
| Acid Clean | Sulfuric Acid | 10% |
| Ambient Rinse | DI Water | |
| Microetch | $H_2O_2 \cdot H_2SO_4$ | 30 min. |
| Ambient Rinse | DI Water | |
| Pre-Dip | Sulfuric Acid | 10% |
| Ambient Rinse | DI Water | |
| Ambient Rinse | DI Water | |
| Direct Immersion-Gold | TCU-36 | 30 min |
| Ambient Rinse | DI Water | |
| Immersion Au | TMX-22 | 16 min |
| Ambient Rinse | DI Water | |
| Hot Rinse | DI Water | |

FIG. 6